Unit: mm

# MA3XD11

### Silicon epitaxial planar type

For high frequency rectification

#### Features

- Forward current (Average)  $I_{F(AV)} = 1$  A rectification is possible
- $\bullet$  Low forward voltage  $V_{\rm F}$

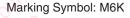
		0.16+0.10
2		0 0 0 0 0 0 0 0
	1.9±0.1 2.90 <sup>+0.05</sup>	LOS.
	000	1: Anode
	EIAJ: SC-59	2: N.C. 3: Cathode Mini3-G1 Package

## Absolute Maximum Ratings $T_a = 25^{\circ}C$

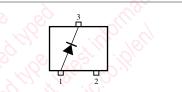
Parameter	Symbol	Rating	Unit
Reverse voltage	VR	20	v
Repetitive peak reverse voltage	V <sub>RRM</sub>	25	V
Forward current (Average) *1	I <sub>F(AV)</sub>	1.0	A
Non-repetitive peak forward surge current *2	I <sub>FSM</sub>	3	А
Junction temperature	Tj	125	°C
Storage temperature	T <sub>stg</sub>	-55 to +125	°C

Note) \*1: Mounted on an alumina PC board

\*2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)



#### Internal Connection



## Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	I <sub>F</sub> = 1.0 A	$\sim 2^{\circ}$		0.45	V
Reverse current	I <sub>R</sub>	$V_R = 20 V$			200	μΑ
Terminal capacitance	Ct	$V_{R} = 0 V, f = 1 MHz$		180		pF

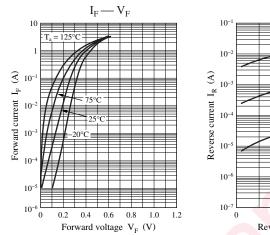
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

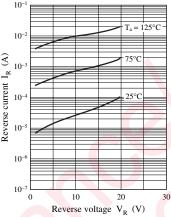
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

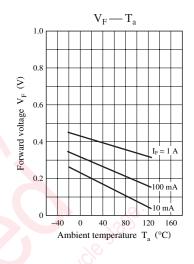
3. Absolute frequency of input and output is 400 MHz.

 $I_R - V_R$ 

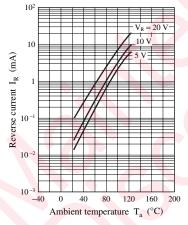
# Panasonic











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